



GSX22N65EF

MOSFET

Metal Oxide Semiconductor Field Effect Transistor

Super Junction MOSFET

650V Super Junction Power Transistor

GSX22N65EF

Data Sheet

Ver 1.1

2018-3-20

650V 22A Power MOSFET

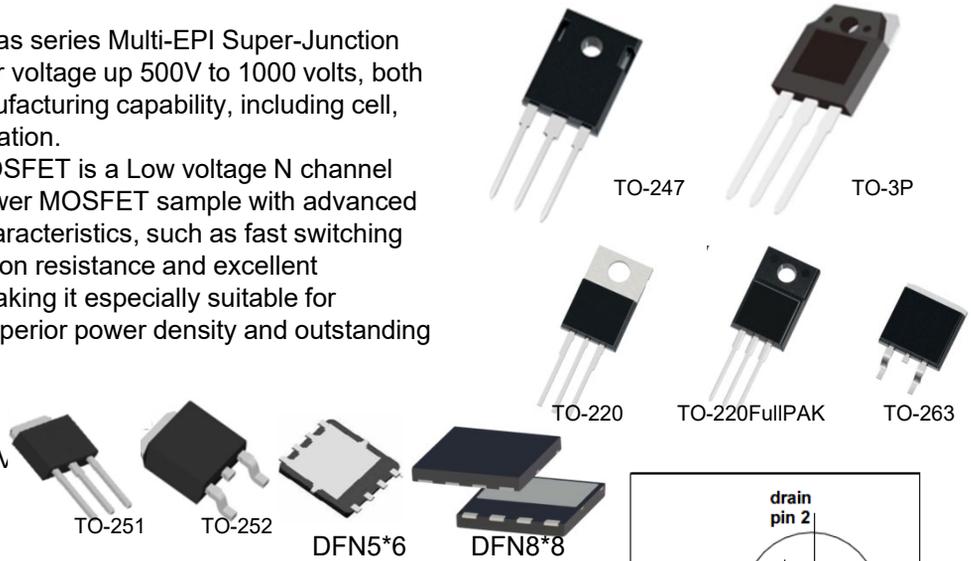
■ Description

Group Semiconductor(GS) has series Multi-EPI Super-Junction power MOSFET platforms for voltage up 500V to 1000 volts, both with design service and manufacturing capability, including cell, termination design and simulation.

The GS 650V 22A power MOSFET is a Low voltage N channel Multi-EPI Super-Junction power MOSFET sample with advanced technology to have better characteristics, such as fast switching time, low Ciss and Crss, low on resistance and excellent avalanche characteristics, making it especially suitable for applications which require superior power density and outstanding efficiency.

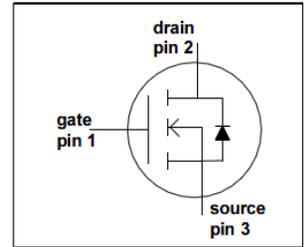
■ Features

RDS(ON)=0.18Ω @VGS = 10V
VDS = 650V
ID (@ VGS=10V) = 11A



■ PKG

GSA22N65EF	GSP22N65EF	GSB22N65EF	GSD22N65EF	GSS22N65EF
TO-220Fullpak	TO-220	TO-263	TO-252	TO-251
GSW22N65EF	GSJ22N65EF	GSN22N65EF	GSM22N65EF	
TO-247	TO-3P	DFN5*6	DFN8*8	



■ Absolute Maximum Ratings (TC = 25° C, unless otherwise specified)

Symbol	Parameter	GSP22N65EF	GSA22N65EF	Unit
V _{DSS}	Drain-Source Voltage	650		V
I _D	Drain Current -Continuous (TC = 25°C)	22*		A
	-Continuous (TC = 100°C)	13*		
I _{DM}	Drain Current - Pulsed (Note 1)	48		A
V _{GSS}	Gate-Source voltage	±30		V
E _{AS}	Single Pulsed Avalanche Energy (Note 2)	485		mJ
I _{AR}	Avalanche Current (Note 1)	3.5		A
E _{AR}	Repetitive Avalanche Energy (Note 1)	1		mJ
dv/dt	Peak Diode Recovery dv/dt (Note 3)	15		V/ns
dV _{ds} /dt	Drain Source voltage slope (V _{ds} =480V)	50		V/ns
P _D	Power Dissipation (TC = 25°C)	151	35	W
T _J , T _{STG}	Operating and Storage Temperature Range	-55 to +150		°C
T _L	Max. Lead Temperature for Soldering Purpose, 1/8" from Case for 5 Seconds	300		°C

650V 22A Power Transistor

■ Electrical Characteristics (T_J=25° C unless otherwise specified)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Off Characteristics						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} = 0V, I _D = 250μA, T _J = 25°C	650	--	--	V
		V _{GS} = 0V, I _D = 250μA, T _J = 150°C	--	700	--	V
ΔBV _{DSS} /ΔT _J	Breakdown Voltage Temperature Coefficient	I _D = 250μA, Referenced to 25°C	--	0.6	--	V/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 650V, V _{GS} = 0V -T _J =25 °C -T _J = 150°C	--	-- 10	1 -	μA μA
I _{GSSF}	Gate-Body Leakage Current, Forward	V _{GS} = 30V, V _{DS} = 0V	--	--	100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse	V _{GS} = -30V, V _{DS} = 0V	--	--	-100	nA
On Characteristics						
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D = 250μA	2	--	4	V
R _{DS(on)}	Static Drain-Source On-Resistance	V _{GS} = 10V, I _D = 11A	--	0.16	0.18	Ω
g _{FS}	Forward Transconductance	V _{DS} = 40V, I _D = 11A	--	16	--	S
Dynamic Characteristics						
C _{iss}	Input Capacitance	V _{DS} = 25V, V _{GS} = 0V, f = 1.0MHz	--	1510	-	pF
C _{oss}	Output Capacitance		--	75	-	pF
C _{rss}	Reverse Transfer Capacitance		--	6	--	pF
Switching Characteristics						
t _{d(on)}	Turn-On Delay Time	V _{DD} = 400V (Note 4)	--	25	--	ns
t _r	Turn-On Rise Time		--	17	--	ns
t _{d(off)}	Turn-Off Delay Time		--	130	--	ns
t _f	Turn-Off Fall Time		--	11	--	ns
Q _g	Total Gate Charge	V _{DS} = 520V, I _D = 11A V _{GS} = 10V (Note 4)	--	90	120	nC
Q _{gs}	Gate-Source Charge		--	8.5	--	nC
Q _{gd}	Gate-Drain Charge		--	13	--	nC
Drain-Source Diode Characteristics and Maximum Ratings						
I _S	Maximum Continuous Drain-Source Diode Forward Current		--	--	20	A
I _{SM}	Maximum Pulsed Drain-Source Diode Forward Current		--	--	60	A
V _{SD}	Drain-Source Diode Forward Voltage	V _{GS} = 0V, I _S = 11A	--	0.9	1.5	V
t _{rr}	Reverse Recovery Time	V _{GS} = 0V, I _S = 11A dI _F /dt = 100A/μs	--	150	--	ns
Q _{rr}	Reverse Recovery Charge		--	5.8	--	μC

NOTES:

1. Repetitive Rating: Pulse width limited by maximum junction temperature
2. L=60mH, I_{AS}=3A, V_{DD}=150V, Starting T_J=25 °C
3. I_{SD}≤4.5A, di/dt ≤ 200A/us, V_{DD} ≤ BV_{DSS}, Starting T_J = 25 °C
4. Pulse Test: Pulse width ≤ 300us, Duty Cycle ≤ 2%
5. Essentially Independent of Operating Temperature Typical Characteristics

650V 22A Power Transistor

■ Thermal Characteristics

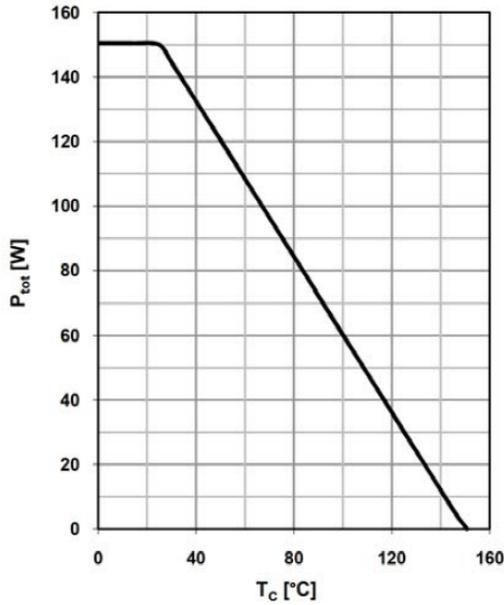
Symbol	Parameter	GSA22N65EF	GSP22N65E F	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	1.2	1.2	°C/W
$R_{\theta CS}$	Thermal Resistance, Case-to-Sink Typ.	0.5	0.5	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	62	62	°C/W

Symbol	Parameter	Value (TO220)	Unit
$R_{\theta JA}^{(6)}$	Maximum Junction-to-Ambient	82	°C/W
$R_{\theta CS}^{(6)}$	Maximum Case-to-sink	0.6	°C/W
$R_{\theta JC}^{(7),(8)}$	Maximum Junction-to-Case θ	4.1	°C/W

1. The power dissipation PD is based on $T_J(\text{MAX})=150^\circ \text{C}$ in a TO251 package, using junction-to-case thermal resistance.
2. Repetitive rating, pulse width limited by junction temperature $T_J(\text{MAX})=150^\circ \text{C}$.
3. $L=1\text{mH}$, Starting $T_J=25^\circ \text{C}$.
4. $L=10\text{mH}$, starting $T_J=25^\circ \text{C}$.
5. $L=60\text{mH}$, starting $T_J=25^\circ \text{C}$.
6. The tests are performed with the device with $T_A=25^\circ \text{C}$.
7. The $R_{\theta JA}$ is the sum of the thermal impedance from junction to case $R_{\theta JC}$ and case to ambient.
8. These curves are based on the junction-to-case thermal impedance, assuming a maximum junction temperature of $T_J(\text{MAX})=150^\circ \text{C}$.

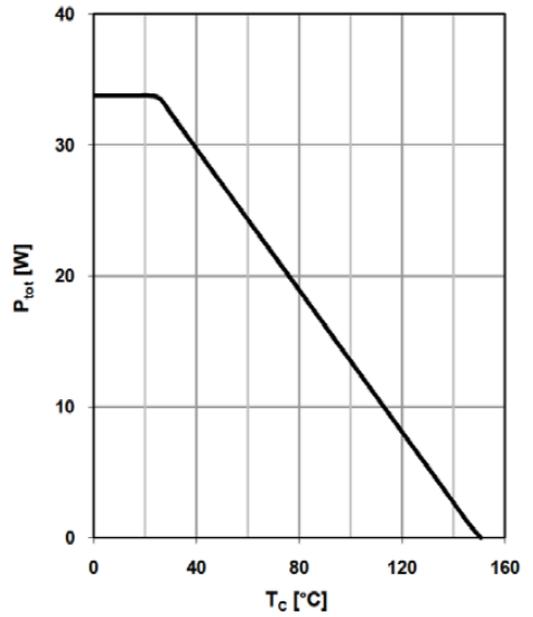
Typical Performance Characteristics

**Power dissipation
Non FullPAK**



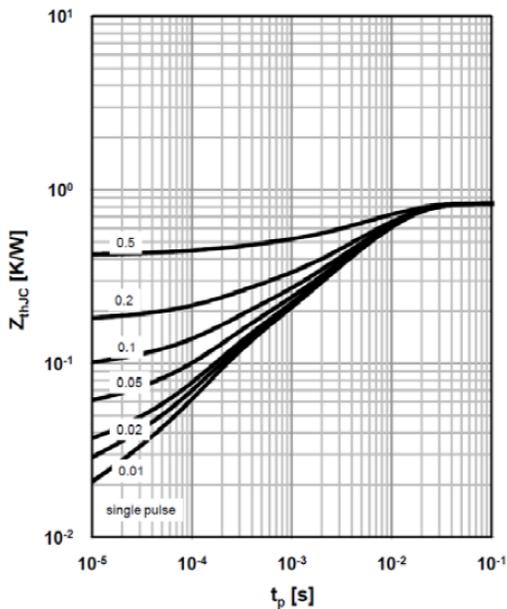
$P_{tot} = f(T_c)$

**Power dissipation
FullPAK**



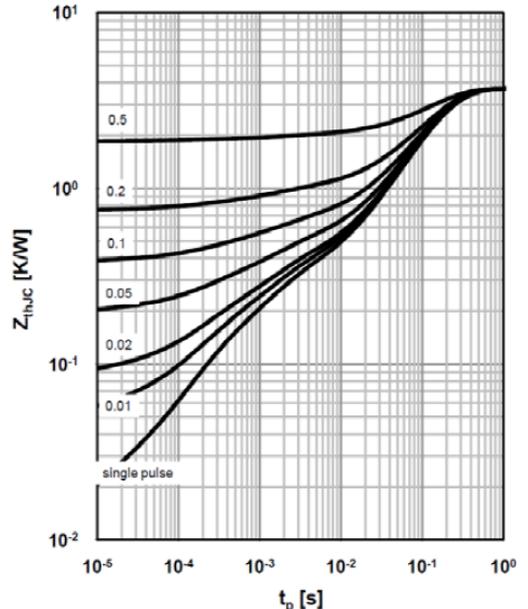
$P_{tot} = f(T_c)$

**Max. transient thermal impedance
Non FullPAK**



$Z_{(thJC)} = f(t_p)$; parameter: $D = t_p/T$

**Max. transient thermal impedance
FullPAK**

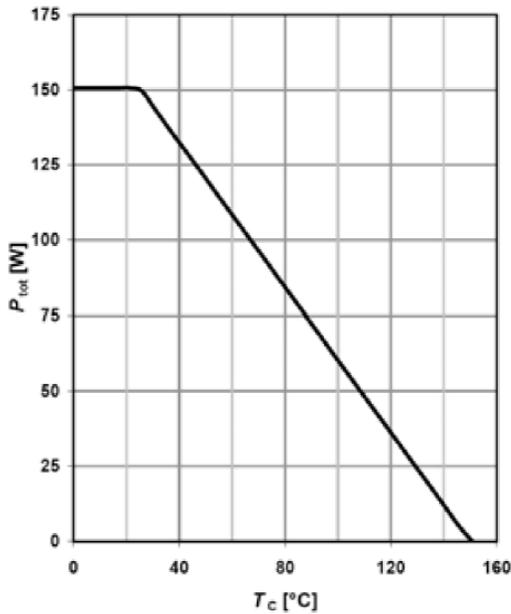


$Z_{(thJC)} = f(t_p)$; parameter: $D = t_p/T$

650V 22A Power Transistor

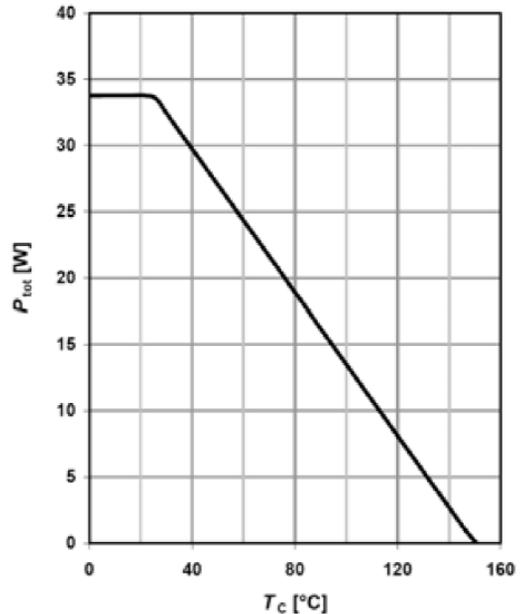
Typical Performance Characteristics

Power dissipation
 TO-220, TO-247, TO-262, TO-263



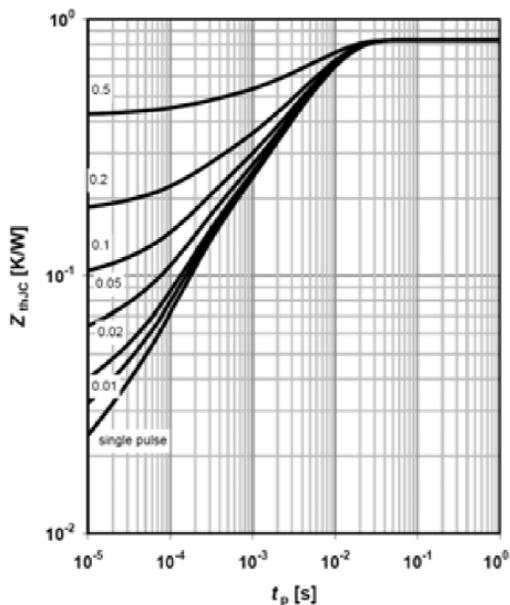
$$P_{tot} = f(T_c)$$

Power dissipation
 TO-220 FullPAK



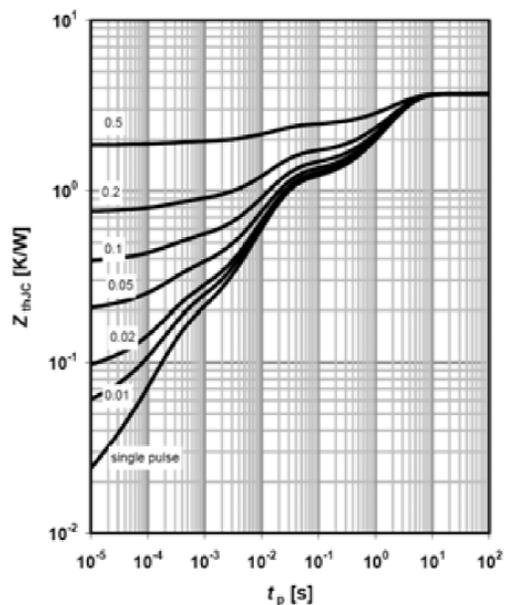
$$P_{tot} = f(T_c)$$

Max. transient thermal impedance
 TO-220, TO-247, TO-262, TO-263



$$Z_{(thJC)} = f(t_p); \text{ parameter: } D = t_p / T$$

Max. transient thermal impedance
 TO-220 FullPAK

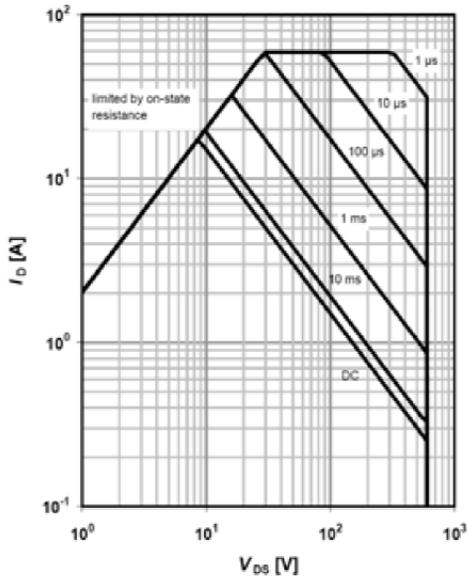


$$Z_{(thJC)} = f(t_p); \text{ parameter: } D = t_p / T$$

650V 22A Power Transistor

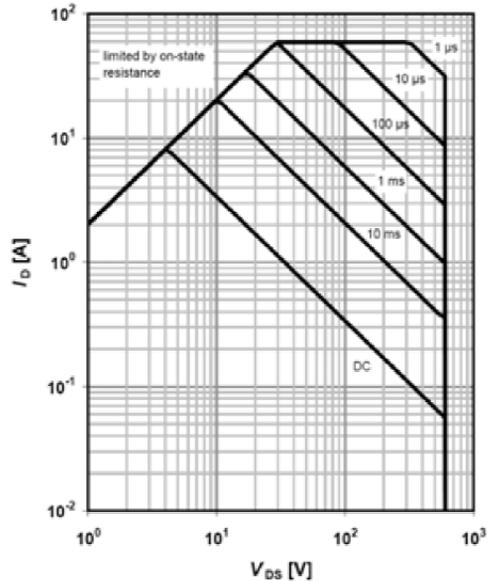
Typical Performance Characteristics

Safe operating area $T_C=25\text{ }^\circ\text{C}$
 TO-220, TO-247, TO-262, TO-263



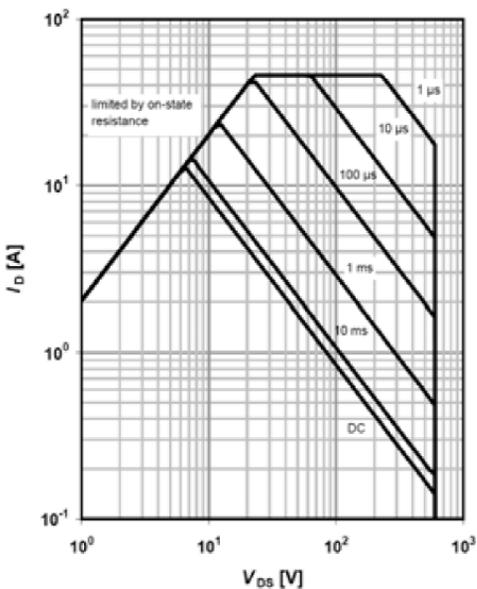
$$I_D=f(V_{DS}); T_C=25\text{ }^\circ\text{C}; D=0; \text{parameter } t_p$$

Safe operating area $T_C=25\text{ }^\circ\text{C}$
 TO-220 FullPAK



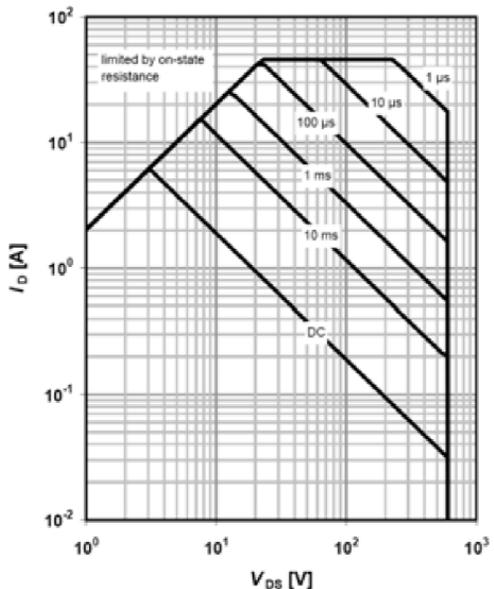
$$I_D=f(V_{DS}); T_C=25\text{ }^\circ\text{C}; D=0; \text{parameter } t_p$$

Safe operating area $T_C=80\text{ }^\circ\text{C}$
 TO-220, TO-247, TO-262, TO-263



$$I_D=f(V_{DS}); T_C=80\text{ }^\circ\text{C}; D=0; \text{parameter } t_p$$

Safe operating area $T_C=80\text{ }^\circ\text{C}$
 TO-220 FullPAK

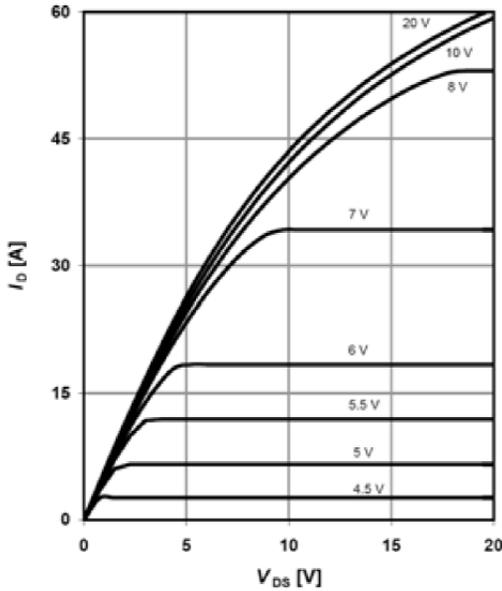


$$I_D=f(V_{DS}); T_C=80\text{ }^\circ\text{C}; D=0; \text{parameter } t_p$$

650V 22A Power Transistor

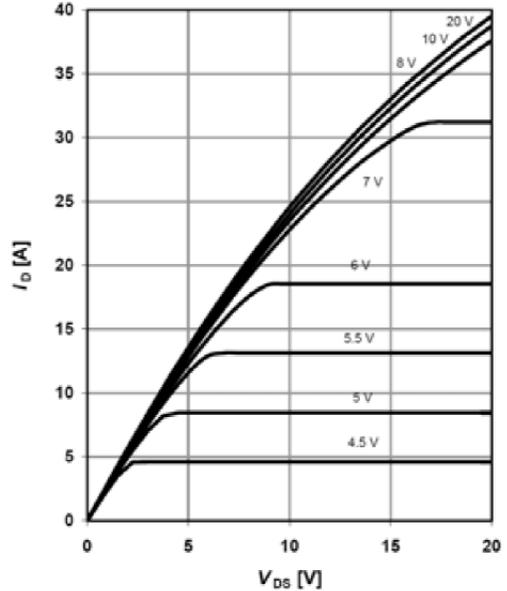
Typical Performance Characteristics

Typ. output characteristics $T_c=25\text{ }^\circ\text{C}$



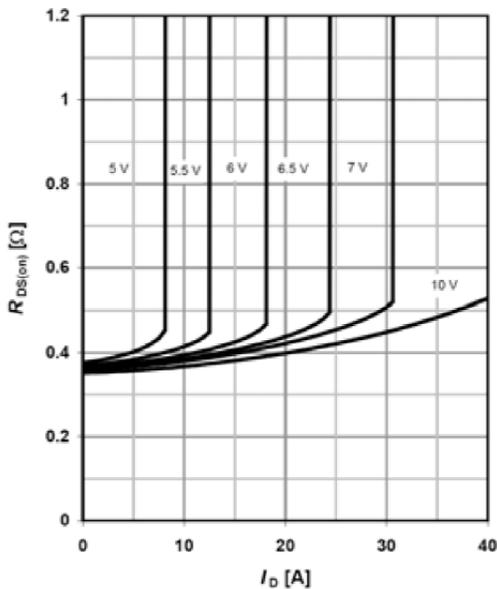
$I_D=f(V_{DS}); T_j=25\text{ }^\circ\text{C};$ parameter: V_{GS}

Typ. output characteristics $T_j=125\text{ }^\circ\text{C}$



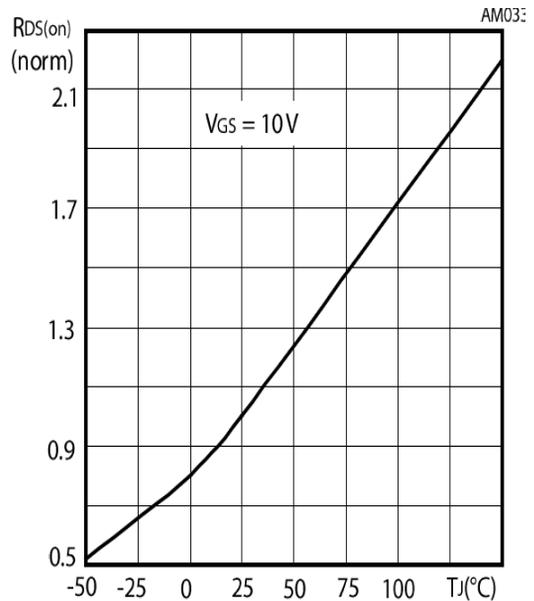
$I_D=f(V_{DS}); T_j=125\text{ }^\circ\text{C};$ parameter: V_{GS}

Typ. drain-source on-state resistance



$R_{DS(on)}=f(I_D); T_j=125\text{ }^\circ\text{C};$ parameter: V_{GS}

Drain-source on-state resistance

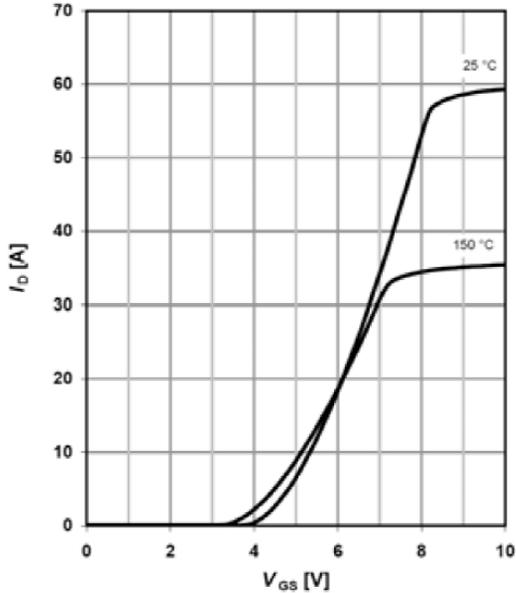


$R_{DS(on)}=f(T_j); I_D=9.5\text{ A}; V_{GS}=10\text{ V}$

650V 22A Power Transistor

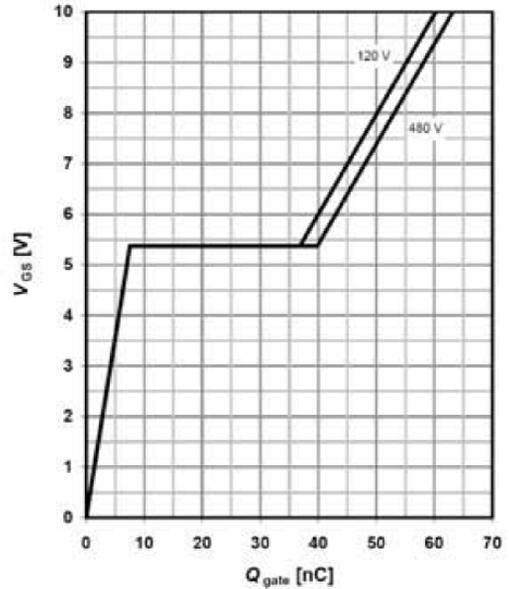
Typical Performance Characteristics

Typ. transfer characteristics



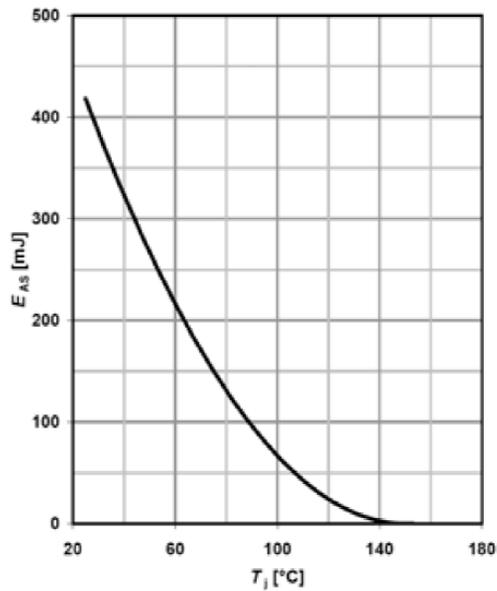
$I_D = f(V_{GS}); V_{DS} = 20V$

Typ. gate charge



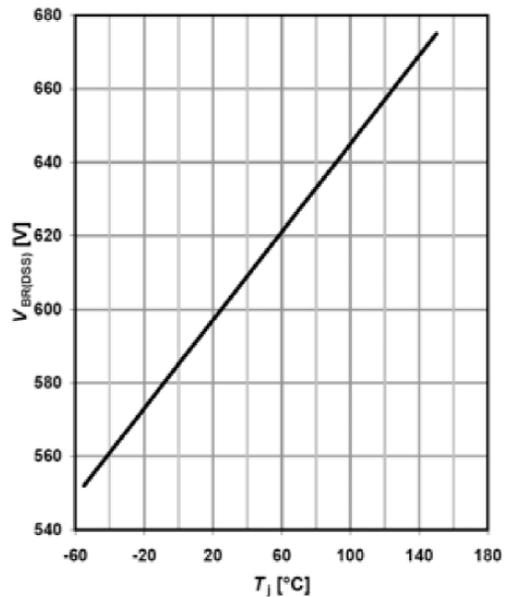
$V_{GS} = f(Q_{gate}); I_D = 9.5A$ pulsed

Avalanche energy



$E_{AS} = f(T_J); I_D = 3.4 A; V_{DD} = 50 V$

Drain-source breakdown voltage



$V_{BR(DSS)} = f(T_J); I_D = 0.25 mA$

650V 22A Power Transistor

Table 20 Switching times test circuit and waveform for inductive load

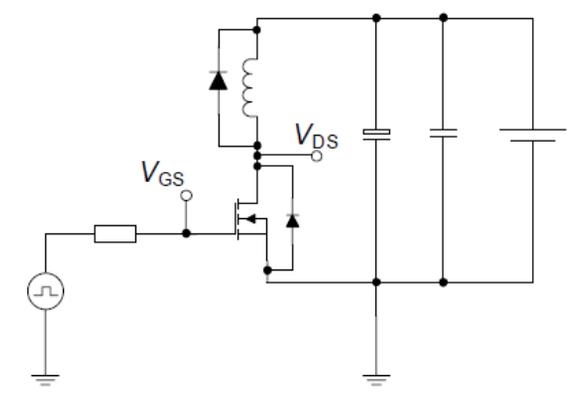
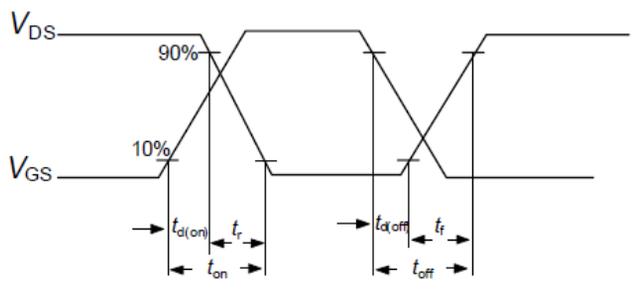
Switching times test circuit for inductive load	Switching time waveform
	

Table 21 Unclamped inductive load test circuit and waveform

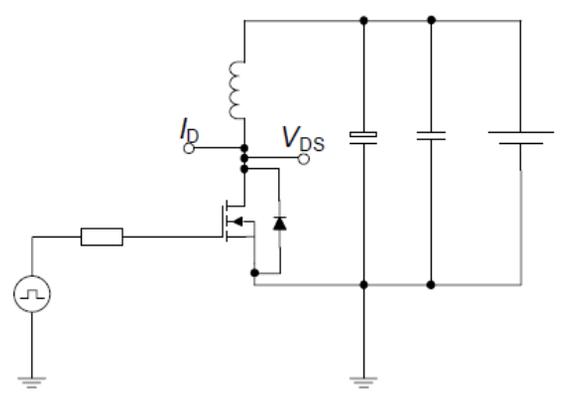
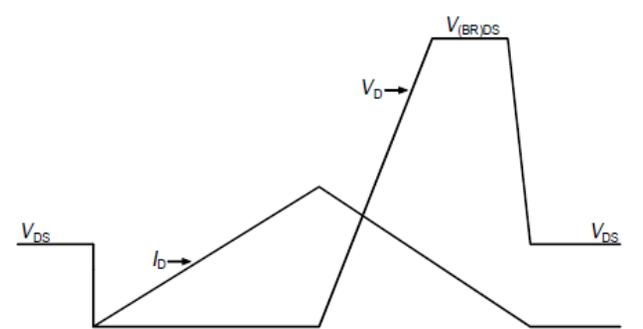
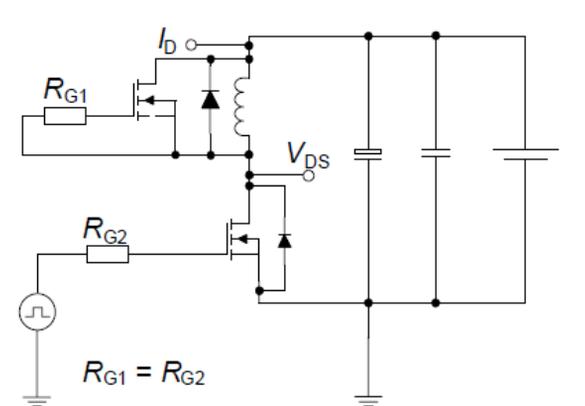
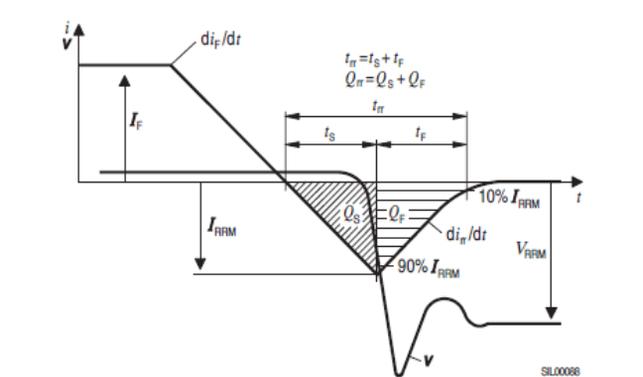
Unclamped inductive load test circuit	Unclamped inductive waveform
	

Table 22 Test circuit and waveform for diode characteristics

Test circuit for diode characteristics	Diode recovery waveform
 <p>$R_{G1} = R_{G2}$</p>	 <p>$t_{rr} = t_s + t_f$ $Q_{rr} = Q_s + Q_f$</p>